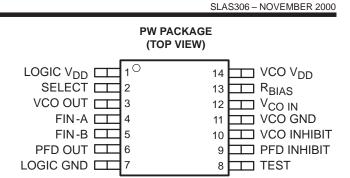
- Voltage-Controlled Oscillator (VCO)
 Ring Oscillator Using Only One External Biasing Resistor (R_{BIAS})
- Recommended Lock Frequency
 100 MHz to 130 MHz
 - (V_{DD} = 3.3 V + 5%, T_A = -20°C to 75°C)
- Phase-Frequency Detector (PFD) Includes a High-Speed Edge-Triggered Detector With Internal Charge Pump
- Independent VCO, PFD Power-Down Mode
- Thin Small-Outline Package (14 Terminal)
- Compatible Pin Assignment to TLC2932, TLC2933



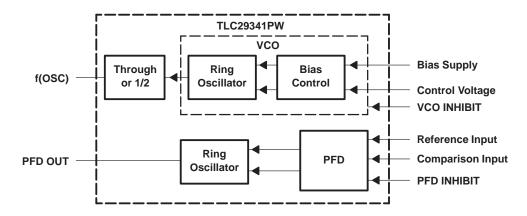
description

The TLC2934, a mixed signal IC designed for phase-locked-loop (PLL) systems, is composed of a voltage-controlled oscillator (VCO) and an edge-triggered-type phase frequency detector (PFD).

The internal VCO is based on the TLC2932 and TLC2933s ring oscillator. It oscillates in wider frequency with lower supply voltage, and it has stable oscillating performance. The oscillation function, provided by only one external resistor connection, supplies bias to the VCI internal circuit. Oscillator range is covered from 10 MHz to 130 MHz with a 3.3-V supply voltage. The VCO has an inhibit function to stop oscillation and for the power-down mode.

The internal PFD, a high-speed rising edge triggered type, has an internal charge pump with a high-impedance output buffer. The PFD detects phase difference between the reference frequency input and the signal frequency input from the VCO output through an external counter device. This functions the same as TLC2932 and TLC2933. The PFD also has the inhibit function for stop phase comparison and for power-down mode.

block diagram





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Terminal Functions

TERMINA	TERMINAL		TERMINAL		ERMINAL		/INAL		
NAME	NO.	1/0	DESCRIPTION						
FIN-A, FIN-B	4 5	I	Frequency signal inputs for PFD. The reference frequency signal (f_{REF-IN}) and the VCO output signal through the external counter device are applied to these terminals. When the LPF design is the lag-lead filter (passive filter and noninverting), $f_{(REF-IN)}$ is input to FIN-A, and the VCO output signal is to FIN-B.						
LOGIC GND	7		GND terminal for the internal logic circuit						
LOGIC V _{DD}	1		Power supply terminal for the internal logic circuit. This power supply terminal separates from VCO $\rm V_{DD}$ to reduce cross-coupling between supplies.						
PFD INHIBIT	9	1	PFD INHIBIT (power-down) control signal input terminal						
PFD OUT	6	0	PFD output terminal. When PFD INHIBIT is high, PFD OUT is in the high-impedance state.						
RBIAS	13	I	Bias resistor (R _{BIAS}) terminal. Connect a resistor between VCO GND and this terminal to supply bias to internal VCO circuit. TLC2934 bias resistor connection is different from TLC2932 and TLC2933, where bias resistor RBIAS is connected to VCO VDD.						
SELECT	2	1	1/2 divider select terminal. L=through output, H=1/2 output.						
TEST	8		Test terminal. Use for production test. Tie to GND when in normal use.						
VCO GND	11		GND terminal for internal VCO						
VCO OUT	3	0	VCO output terminal. When VCO INHIBIT = high, VCO OUT is low.						
VCO INHIBIT	10	Ι	VCO INHIBIT (power-down) control signal input terminal						
VCO IN	12	1	VCO control voltage input terminal. Normally, The external LPF is connected to this terminal.						
VCO V _{DD}	14		Power supply terminal for the internal VCO circuit. This power supply terminal should be separate from LOGIC V_{DD} to reduce cross-coupling between supplies.						

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage (each supply), V _{DD} (see Note 1)	–0.5 V to 4 V
Input voltage range (each input), V_I (see Note 1)	. –0.5 V to V _{DD} + 0.5 V
Input current (each input), I	±20 mA
Output current (each output), IO	±20 mA
Continuous total power dissipation at (or below) $T_A = 25^{\circ}C$ (see Note 2), P_D	700 mW
Operating free-air temperature range. T _A	–20°C to 75°C
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.

2. For operation above 25°C free-air temperature, derate linearly at the rate of 5.6 mW/°C



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recommended operating conditions

		MIN	TYP	MAX	UNIT
Supply voltage (each supply, V _{DD} (see Notes 3 and 4)	3.15	3.3	3.45	V
Input voltage (each input except for	VCO IN, VI	0		V _{DD}	V
Output current (each output), IO		0		±2	mA
VCO control voltage, VCO IN		0.5		V _{DD}	V
	$R_{BIAS} = 1 k\Omega$	36		130	MHz
Lock frequency (through output)	R _{BIAS} = 1.8 kΩ	28		90	
	$R_{BIAS} = 2.4 \text{ k}\Omega$	26		80	
	$R_{BIAS} = 3.3 \text{ k}\Omega$	0 Vpi 0 ± 0.5 Vpi 36 13 28 9 26 8 20 6 18 6 14 4 13 4 10 3 1.0 3. -20 7	60		
	$R_{BIAS} = 1 k\Omega$	18		65	MHz
Look fraguanay (1/2 autout)	R _{BIAS} = 1.8 kΩ	14		45	
Lock frequency (1/2 output)	$R_{BIAS} = 2.4 \text{ k}\Omega$	13		40	
	$R_{BIAS} = 3.3 \text{ k}\Omega$	10		30	
Bias resistor, R _{BIAS}		1.0		3.3	KΩ
Operating temperature range, TA		-20		75	°C
V _{CO IN} voltage at VCO INHIBIT \downarrow , V	(CINH) (see Note 5)		0	0.5	V

NOTES: 3. It is recommended that the logic supply terminal (LOGIC V_{DD}) and the VCO supply terminal (VCO V_{DD}) be at the same voltage and separated from each other.

4. A bypass capacitor is placed as close as possible to each supply terminal.

5. For stable restart of VCO, V_{COIN} is 0 V when VCO INHIBIT is pulled down to GND level to disable the VCO INHIBIT function. And also, V_{CO IN} should be 0 V when the operation will be started by supplying the power.

electrical characteristics over recommended operating free-air temperature range, V_{DD}=3.3 V (unless otherwise noted)

VCO

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VOH	High-level output voltage	$I_{OH} = -2 \text{ mA}$	3.1			V
VOL	Low-level output voltage	I _{OL} = 2 mA			0.2	V
VIH	High-level input voltage	Logic signal input	2.3			V
VIL	Low-level input voltage	Logic signal input			1.0	V
lj	Input current at TEST, VCO INHIBIT	$V_I = V_{DD}$ or GND			±1	μΑ
ZV(CO IN)	Input impedance at V _{COIN}	$V_{COIN} = 1/2 V_{DD}$		10		MΩ
IDD(INH)	VCO supply current (inhibit)	See Note 6		0.01	1	μΑ
IDD(VCO)	VCO supply current	See Note 7		10	15	mA

NOTES: 6. Current into VCO V_{DD} , when VCO INHIBIT = V_{DD} , PFD is inhibited.

7. Current into VCO V_{DD}, when V_{COIN} = 1/2 V_{DD}, R_{BIAS} = 1 k Ω , VCO INHIBIT = GND, PFD is inhibited.

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electrical characteristics over recommended operating free-air temperature range, V_{DD}=3.3 V (unless otherwise noted) (continued)

VCO

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VOH	High-level output voltage	$I_{OH} = -2 \text{ mA}$	3.1			V
VOL	Low-level output voltage	I _{OL} = 2 mA			0.2	V
I _{OZ}	High-impedance state output current	PFD INHIBIT = high, $V_O = V_{DD}$ or GND			±1	μA
VIH	High-level input voltage at FIN–A,B		2.3			V
VIL	Low-level input voltage at FIN–A,B				1.0	V
V _(TO)	Positive input threshold voltage at PFD INHIBIT		1.0	1.65	2.3	V
CI	Input capacitance at FIN-A,B			5		pF
Z _(IN)	Input impedance at FIN-A,B			10		MΩ
IDD(PFD)	PFD supply current	See Note 8		1.5	6.0	mA

NOTE 8: Current into LOGIC V_{DD}, when FIN-A, FIN-B=50 MHz ($V_{I(pp)}$ = 3.3V, rectangular wave), Test=GND, no load, and VCO OUT is inhibited.

VCO

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
f(OSC) Operating oscillation frequency		oscillation frequency $R_{BIAS} = 1 k\Omega$					
^t (STB)	Time to stable oscillation	See Note 9		0.7	10	μs	
t _r	Rise time	C _L = 15 pF, See Figure 3		1.7	5	ns	
t _f	Fall time	C _L = 15 pF, See Figure 3		1.1	4	ns	
^f (duty)	Duty cycle at VCO OUT	$R_{BIAS} = 1.0 \text{ k}\Omega, V_{CO IN} = 1/2 \text{ V}_{DD}$	45%	50%	55%		
	Temperature coefficient of oscillation frequency	$ \begin{array}{l} R_{BIAS} = 1.0 \mathrm{k}\Omega, \ V_{CO} \ IN = 1/2 \ V_{DD}, \\ T_{A} = -20^\circ \mathrm{C} \ \mathrm{to} \ 75^\circ \mathrm{C} \end{array} $		0.03		%/°C	
	Supply voltage coefficient of oscillation frequency	$R_{BIAS} = 1 k\Omega$, V _{CO IN} = 1.65 V, V _{DD} = 3.15 V to 3.45 V		0.02		%/mV	
	Jitter absolute	$R_{BIAS} = 1 \text{ k}\Omega$, $V_{CO IN} = 1/2 \text{ V}_{DD}$		50		ps	

NOTE 9: Current into VCO V_DD, when VCO INHIBIT = V_DD, PFD is inhibited.

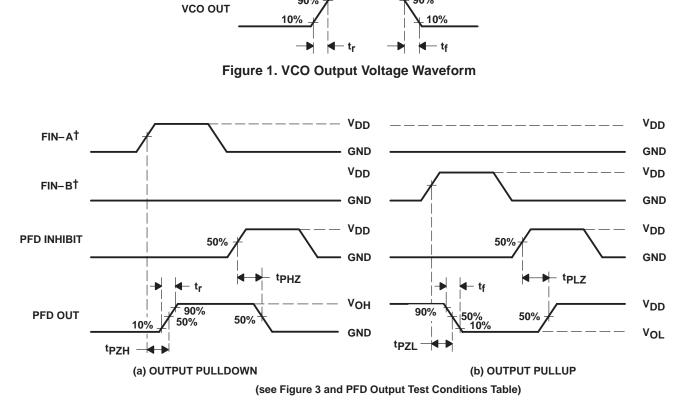
PFD AC

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fMAX	Maximum operating frequency		50			MHz
^t PLZ	PFD output disable time from low level	See Figures 4 and 5 and Table 6		15.3	40	ns
^t PHZ	PFD output disable time from high level			15.5	40	ns
tPZL	PFD output enable time from low level			2.4	10	ns
^t PZH	PFD output enable time from high level			2.5	10	ns
tr	Rise time	C _L =15 pF (see Figure 3)		1.2	5	ns
t _f	Fall time	C _L =15 pF (see Figure 3)		0.7	5	ns



90%

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PARAMETER MEASUREMENT INFORMATION

90%

 † FIN-A and FIN-B are for reference phase only, not for timing.



PFD Output Test Conditions									
PARAMETER	RL	CL	SL	S ₂					
^t PZH									
^t PHZ			Open	Close					
tr	1 kΩ	15 pF							
^t PZL	1 652	тэрг							
^t PLZ			Close	Open					
tf									

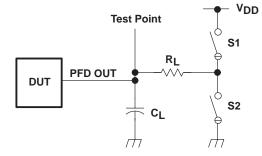
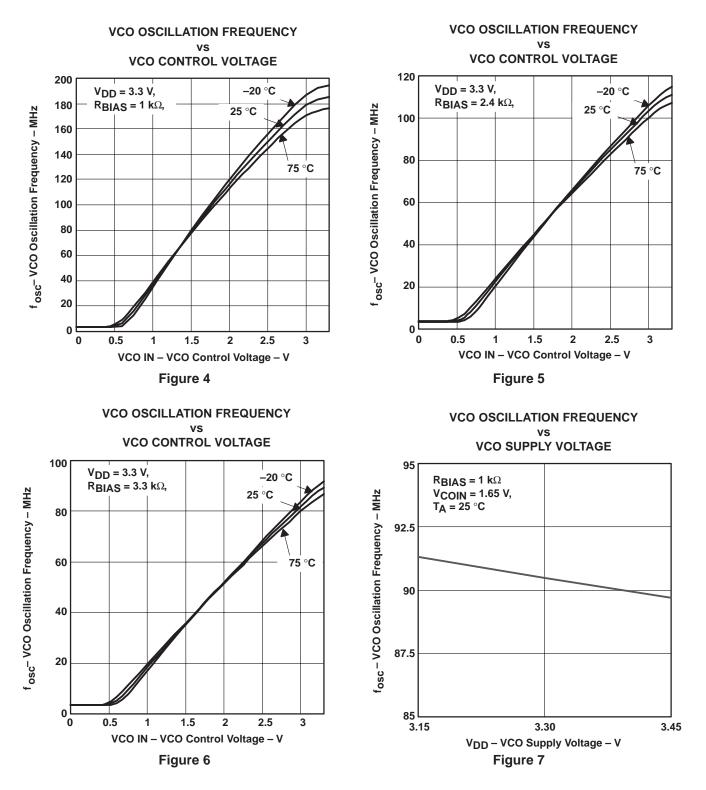


Figure 3. PFD Output Test Condition



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TLC2934IPW	NRND	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLC2934IPWG4	NRND	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLC2934IPWR	NRND	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

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the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*	All dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	TLC2934IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC2934IPWR	TSSOP	PW	14	2000	367.0	367.0	35.0

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